Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of the Claims:

Claim 1 (currently amended): A method for producing a structure on a substrate comprising the steps of ~~depositing drops of a suspension of nanoparticles of a material in a liquid by means of a droplet generator, melting the nanoparticles of the deposited drops at least partially by exposition to laser light and solidifying the molten nanoparticles for forming the structure.~~

a) depositing drops of a suspension onto a substrate,

wherein said suspension comprises nanoparticles of a material suspended in a liquid; and,

wherein said substrate lacks recesses in the region where said drops are deposited onto said substrate; and,

b) exposing said nanoparticles on said substrate to at least one localized spot of laser light such that said nanoparticles are at least partially melted by said at least one localized spot of laser light; and,

c) solidifying said at least partially melted nanoparticles, forming thereby said structure on said substrate.

Claim 2 (currently amended): The method of claim 1 further comprising the steps of

directing ~~the~~ said at least one localized spot of laser light to ~~a~~ at least one curing point on ~~the~~ said substrate and

translating ~~the~~ said at least one curing point ~~in respect to the~~ over said substrate.

Claim 3 (currently amended): The method of claim 1 further comprising the steps of

depositing ~~the~~ said drops at a drop-off point on said substrate and

translating ~~the~~ said drop-off point ~~in~~ with respect to ~~the~~ said substrate.

Claim 4 (currently amended): The method of claim 1 further comprising the steps of

directing ~~the~~ said at least one localized spot of laser light to a curing point on ~~the~~ said substrate,

depositing ~~the~~ said drops at a drop-off point on said substrate, and

translating ~~the~~ said curing point and ~~the~~ said drop-off point ~~in respect to the~~ over said substrate.

Claim 5 (currently amended): The method of claim 4 wherein ~~the~~ said curing point and ~~the~~ said drop-off point coincide.

Claim 6 (currently amended): The method of claim 4 wherein ~~the~~ said curing point and ~~the~~ said drop-off point are located at a distance from each other.

Claim 7 (currently amended): The method of claim 1 further comprising the step of generating ~~the~~ said drops by compressing a volume of ~~the~~ said suspension and thereby

squirting ~~the~~ said drops through an opening onto ~~the~~ said substrate.

Claim 8 (currently amended): The method of claim 1 wherein ~~the~~ said liquid is selected from the group ~~comprising~~ consisting of toluene, terpineol, xylene, ~~and~~ water and mixtures thereof.

Claim 9 (currently amended): The method of claim 1 wherein ~~an~~ the exponential absorption coefficient of ~~the~~ said at least one localized spot of laser light in ~~the~~ said suspension is at least approximately 0.1 μm^{-1}~~, in particular at least 1 μm^{-1}~~.

Claim 10 (currently amended): The method of claim 1 wherein ~~the~~ said suspension is deposited as a layer on ~~the~~ said substrate and wherein at least 80% of ~~the~~ said at least one localized spot of laser light is absorbed in ~~the~~ said layer.

Claim 11 (currently amended): The method of claim 1 wherein ~~the~~ said nanoparticles ~~are of a~~ comprise at least one metal.

Claim 12 (currently amended): The method of claim 1 wherein ~~the~~ said liquid comprises toluene and ~~the~~ said nanoparticles comprise gold.

Claim 13 (currently amended): The method of claim 1 wherein ~~an average diameter of~~ the size of said nanoparticles is sufficiently small ~~for reducing a~~ that the melting point of ~~the~~said nanoparticles is substantially below ~~a bulk~~ the melting point of the bulk material comprising said nanoparticles.

Claim 14 (currently amended): The method of claim 1 wherein an average diameter of ~~the~~ said nanoparticles is less than approximately 100 nm~~, in particular less than 10 nm, preferably between 1 nm and 5 nm~~.

Claim 15 (currently amended): The method of claim 1 wherein ~~the~~ said structure is a superconductor.

Claim 16 (currently amended): The method of claim ~~1~~2 wherein an intensity distribution of ~~the~~ one or more of said at least one localized spot of laser light at ~~the~~ said curing point is non-Gaussian.

Claim 17 (currently amended): The method of claim ~~1~~2 wherein an intensity distribution of ~~the~~ one or more of said at least one localized spot of laser light at ~~the~~ said curing point has at least two spatially separated maxima.

Claim 18 (currently amended): The method of claim ~~1~~2 ~~comprising the step of depositing~~ wherein said drops are deposited along a line strip on said substrate, wherein an intensity distribution of ~~the~~ said at least one localized spot of laser light at ~~the~~ said curing point ~~has~~ has a local minimum on a center line of said line strip.

Claim 19 (currently amended): The method of claim ~~1~~2 ~~comprising the steps of~~

~~depositing~~wherein said drops are deposited along a line strip on said substrate, wherein said exposing of said nanoparticles comprises

directing at least two laser beams onto said substrate at said curing point, such that said laser beams ~~impinging~~ impinge on opposite sides of a center line of said line strip.

Claim 20 (currently amended): The method of claim 1 ~~comprising the step of repetitively pulsing said laser light~~ wherein said at least one localized spot of laser light is pulsed.

Claim 21 (currently amended): The method of claim 1 further comprising immediately following step (a), the step of _____ a_1) evaporating at least part of said liquid. ~~after depositing said drops and before bringing said nanoparticles into contact with said laser light~~.

Claim 22 (currently amended): The method of claim 1 further comprising the step of heating said substrate by a means separate from said laser light.

Claim 23 (currently amended): The method of claim 1 wherein said substrate is transparent ~~for~~ to said laser light.

Claim 24 (currently amended): The method of claim 1 further comprising the step of generating, above or below said structure, a ~~structured~~ polymer layer by _____ depositing drops of a polymerizable liquid, and _____ polymerizing said drops of deposited polymerizable liquid.

Claim 25 (original): The method of claim 24, wherein said drops of deposited polymerizable liquid are polymerized using UV radiation.

Claims 26-29 (canceled)

Claims 30-34 (withdrawn)

Claim 35 (new): The method of claim 9 wherein said exponential absorption coefficient of said at least one localized spot of laser light in said suspension is at least approximately 1 μm^{-1}.

Claim 36 (new): The method of claim 14 wherein said average diameter of said nanoparticles is less than approximately 10 nm.

Claim 37 (new): The method of claim 36 wherein said average diameter of said nanoparticles in the range from approximately 1 nm to approximately 5 nm.

Claim 38 (new): A method for making a capacitor comprising:

a) depositing a first electrically conductive structure on an insulating substrate as in claim 1; and,

b) depositing a dielectric structure on said conductive structure as in claim 24; and,

c) depositing a second electrically conductive structure on said dielectric structure as in claim 1 such that said first conductive structure and said second conductive structure surround said dielectric structure forming thereby a capacitor.

Claim 39 (new): A method for crossing a first electrical conductor and a second electrical conductor on an insulating substrate while maintaining electrical isolation between said first and second electrical conductors, comprising:

a) depositing a first electrically conductive structure on an insulating substrate as in claim 1; and,

b) depositing an insulating structure on said conductive structure as in claim 24; and,

c) depositing a second electrically conductive structure on said insulating structure as in claim 1 such that said first conductive structure and said second conductive structure are separated by said insulating structure and maintain electrical isolation thereby.